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(71) Applicant (for all designated States except US): DOW CORNING CORPORATION [US/US]; 2200 West Salzburg Road, Midland, MI 48686-0994 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): BECKER, Gregory [US/US]; 3347 Douglas Drive, Sanford, MI 48657 (US). GARDNER, Geoffrey [US/US]; 5042 North Fox Road, Sanford, MI 48657 (US). HARKNESS, Brian [US/US]; 5411 Wanetah Drive, Midland, MI 48640 (US).

(74) Common Representative: DOW CORNING CORPORATION; 2200 West Salzburg Road, Midland, MI 48686-0994 (US).

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(54) Title: METHOD FOR ETCHING A PATTERNED SILICONE LAYER

(57) Abstract: A method for reworking semiconductor materials includes: (i) applying a silicone composition to a surface of a substrate to form a film, (ii) exposing a portion of the film to radiation to produce a partially exposed film having non-exposed regions covering a portion of the surface and exposed regions covering the remainder of the surface; (iii) heating the partially exposed film for an amount of time such that the exposed regions are substantially insoluble in a developing solvent and the non-exposed regions are soluble in the developing solvent; (iv) removing the nonexposed regions of the heated film with the developing solvent to form a patterned film; (v) heating the patterned film for an amount of time sufficient to form a cured silicone layer; and (vi) removing all or a portion of the cured silicone layer by exposure to an anhydrous etching solution including an organic solvent and a base.



WO 2005/017627 A1